



EDGE PLATE DETAIL, 4X

⊗ DENOTES EDGE PLATING LOCATION

SIZE	QTY	SYM	PLATED	TOL
10	111	+	YES	+/-3 FILLED
14	234	×	YES	+/-3

NEXT ASSY	USED ON
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UNLESS OTHERWISE SPECIFIED:	
DIMENSIONS ARE IN INCHES [mm]	
DRAWING PRACTICES PER ASME Y14.100	
INTERPRET DIMENSIONS & TOLERANCES PER ASME Y14.5-2009	
TOLERANCES:	
.XX	± .01
.XXX	± .005
.XXXX	± .0020
ANGLES	± .5 DEG.

DRAWN BY DONOVAN	DATE DRN 01/14/2010
CHECKED BY KEITH BENSON ENGINEER	
THIRD ANGLE PROJECTION	
DO NOT SCALE DRAWING	

PROPRIETARY TO HITTITE MICROWAVE CORPORATION			
HITTITE MICROWAVE CORPORATION 20 Alpha Road Chelmsford, MA 01824			
TITLE PCB, GENERIC LS7 EVAL			
SIZE A	CODE ID NO. 1CN88	DWG NO. 128997	REV 3
SCALE: 1:1		WT:	SHEET: 1 OF 1

REVISION			
LTR	DESCRIPTION	DATE	APPROVED
2	REVISED FORMAT & ADDED CAPS	8/16/10	V. LY
3	CHANGED CONNECTORS TO TRIMLESS LAUNCH	6/15/11	M. GIRDVAINIS

SILKSCREEN-01	
SOLDERMASK-01	
METAL-01	1/2oz Cu
ARLON OR R04350 Core	.010 ±.001 (CRITICAL)
METAL-02	1/2oz Cu

LAYER STACKUP

NOTES:

UNLESS OTHERWISE SPECIFIED:

1. MATERIAL: PER LAYER STACKUP AS SHOWN. TYPE ARLON 25FR OR ROGERS 4350, HALF OUNCE COPPER BOTH SIDES.
2. FINISH: GOLD PLATE PER ASTM B-488, TYPE III, CODE A, 8 TO 40 MICROINCHES, OVER NICKEL PER QQ-N-290, 100 MICROINCHES MINIMUM.
3. PLATED THRU HOLES: .001 MINIMUM WALL THICKNESS.
4. HOLE SIZES AND POSITIONS PER ARTWORK AND/OR DRILL FILE.
5. ALL HOLES TO BE LOCATED WITHIN ±.003 OF THE CENTER OF THE PAD OR OTHER TRUE POSITION.
6. FRONT TO BACK REGISTRATION ±.003 MAX.
7. BOARD WARPAGE: <.010 PER LINEAR INCH.
8. SILKSCREEN TOP SIDE ONLY WITH WHITE EPOXY INK.
9. SOLDERMASK: LPI SOLDERMASK TOP SIDE. COLOR: GREEN REGISTRATION: ±.004 MAX.
10. "SIZE" IN DRILL LEGEND IS IN MILS AND REFERS TO FINISHED HOLE SIZE.
11. MANUFACTURE PER IPC-6012 CLASS 2.
12. PLATING THICKNESS .002 ±.0005 FOR METAL-01 AND METAL-02.
13. ARTWORK IS 1:1. VENDOR TO ADJUST FOR ETCH FACTOR.

SPECIAL REQUIREMENTS:

14. CRITICAL LINE WIDTH = .018 ±.001 ON METAL-01. ADJUST PROCESS TO ACHIEVE WIDTH.
15. ALL .010 VIAS TO BE FILLED WITH NON-CONDUCTIVE VIA FILL AND OVERPLATED WITH Cu BOTH SIDES.
16. EDGE PLATING MUST CONNECT BOTH METAL LAYERS.

VENDOR NOTES:

17. VENDOR MAY ADD E-TEST STAMP TO PCB. VENDOR SHALL NOT ADD NAME, LOGO, DATE CODE, UL LISTING OR ANY OTHER MARKING TO ANY VISIBLE LAYER.
18. BOARDS MUST PASS VISUAL INSPECTION PER IPC-A-600 CLASS 2.